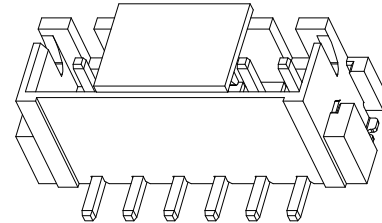
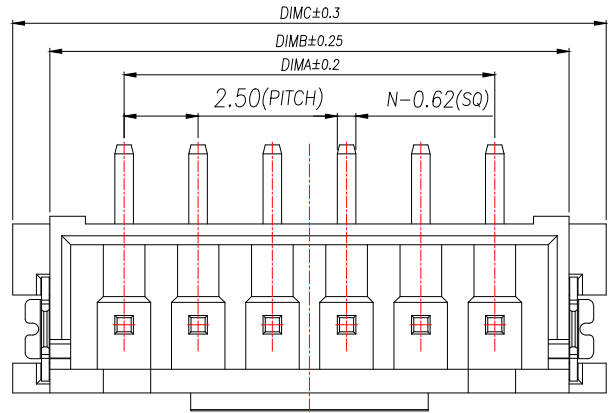


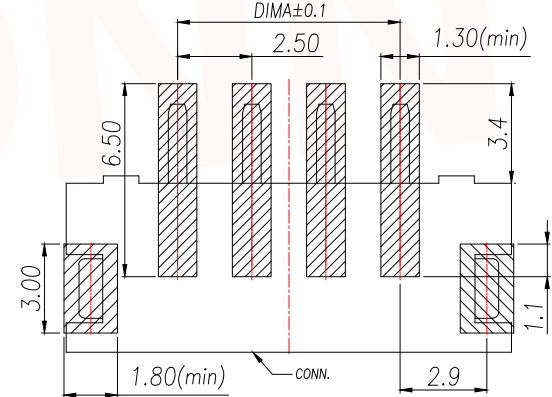
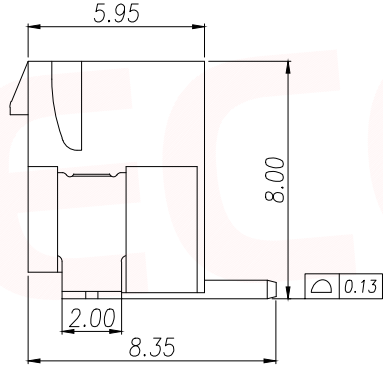
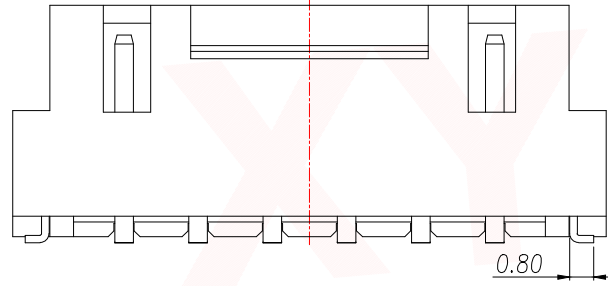
REV.	Q'TY	ECN. NO.	APR.	DATE



PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

NOTES:

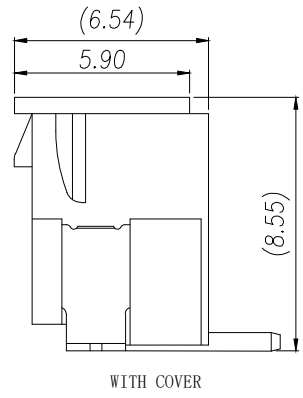
- Working temp:-25°C~85°C.
- Voltage rating:250V AV/DC(rms)
- Contact resistance:20mΩ max.
- Insulation resistance:1000MΩ min.
- Current rating:3A AV/DC
- Withstanding Voltage:1000V AC/minute
- Pin Retention Force:15N min.
- Housing material:LCP UL94-V0,Natural
- Terminal mater:Brass,
plating Ni 50u" min , plating Tin 100u"min.
- Solder tab material:Brass,
plating Ni 50u" min , plating Tin 100u"min.



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)

▨ SMT SOLDER AREA

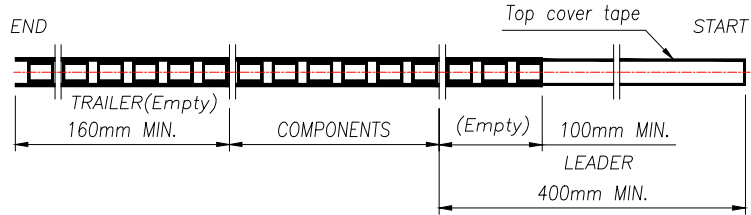
PIN	NO.	Dim A	Dim B	Dim C
2	XY-XHB2.5-2A51	2.50	7.50	10.00
3	XY-XHB2.5-3A51	5.00	10.00	12.50
4	XY-XHB2.5-4A51	7.50	12.50	15.00
5	XY-XHB2.5-5A51	10.00	15.00	17.50
6	XY-XHB2.5-6A51	12.50	17.50	20.00
7	XY-XHB2.5-7A51	15.00	20.00	22.50
8	XY-XHB2.5-8A51	17.50	22.50	25.00
9	XY-XHB2.5-9A51	20.00	25.00	27.50
10	XY-XHB2.5-10A51	22.50	27.50	30.00
11	XY-XHB2.5-11A51	25.00	30.00	32.50
12	XY-XHB2.5-12A51	27.50	32.50	35.00
13	XY-XHB2.5-13A51	30.00	35.00	37.50
14	XY-XHB2.5-14A51	32.50	37.50	40.00
15	XY-XHB2.5-15A51	35.00	40.00	42.50
16	XY-XHB2.5-16A51	37.50	42.50	45.00



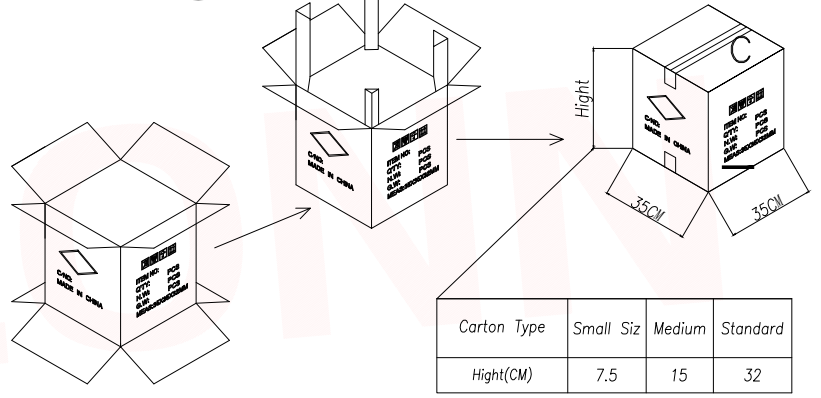
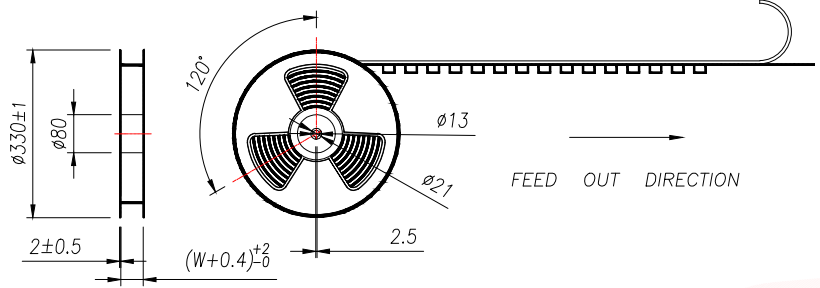
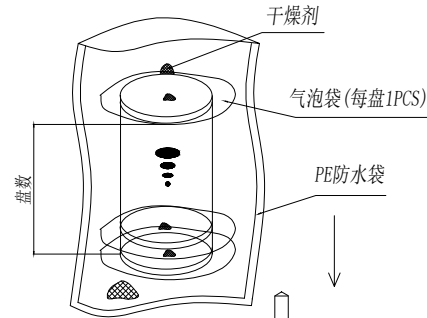
WITH COVER

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X±0.35	X.*± 5°	APR.	Alex	TITLE: WAFER 2.50mm H8.0mm W/B 180°SMT
.XX±0.25	.X.*± 3°	CHK.	Jack	DWG NO. XY-XHB2.5-NA51
.XXX±0.15	.XX.*± 1°	DRA.	Can	PROJ. CUSTOMER DRAWING
		SIZE A4	SCALE 1:1	SHEET 1/3
				REV. A

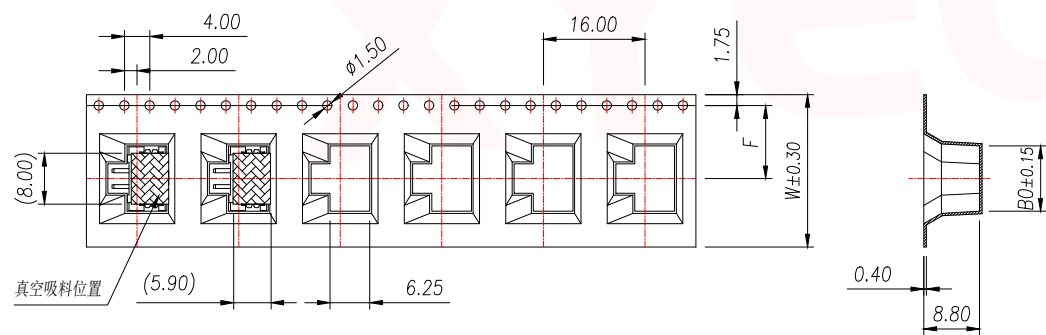
REV.	Q'TY	ECN. NO.	APR.	DATE



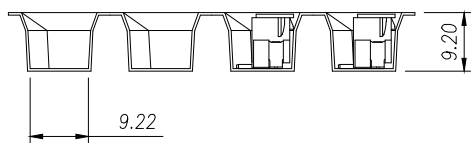
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Carton Type	Small Siz	Medium	Standard
Hight(CM)	7.5	15	32



- NOTE:
- 1.10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE $\pm 0.2\text{mm}$.
 - 2.CARRIER CAMBER NOT TO EXCEED 1mm IN 100mm.
 - 3.ALL DIMENSIONS MEET EIA-481 REQUIREMENTS.
 - 4.MATERIAL: CLEAR ANTISTATIC PS, COLD SEALING.
 - 5.THICKNESS: $0.40 \pm 0.05\text{mm}$.
 - 6.PACKING LENGTH PER REEL: 8.4 METERS.
 - 7.COMPONENT LOAD PER REEL: 500 PCS.



PIN	NO.	Dim B0	Dim W	Dim F	PCS/RELL	RELL/CARTON	PCS/CARTON
2	XY-XHB2.5-2A51	10.30	24.00	11.50	500	10	5000
3	XY-XHB2.5-3A51	12.80					
4	XY-XHB2.5-4A51	15.30					

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X ± 0.35	X.* $\pm 5^\circ$	APR.	Alex	TITLE: WAFER 2.50mm H8.0mm W/B 180°SMT	
.XX ± 0.25	.X.* $\pm 3^\circ$	CHK.	Jack	DWG NO. XY-XHB2.5-NA51	
.XXX ± 0.15	.XX.* $\pm 1^\circ$	DRA.	Can	PROJ.	CUSTOMER DRAWING
		SIZE A4	SCALE 1:1	SHEET 2/3	REV. A

